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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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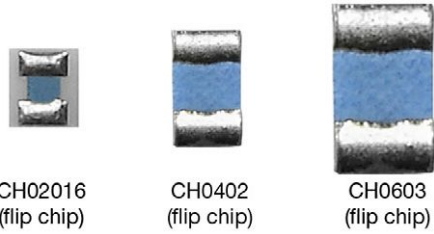
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High Frequency 50 GHz Thin Film Chip Resistor


 CH02016
(flip chip)

 CH0402
(flip chip)

 CH0603
(flip chip)

DESIGN SUPPORT TOOLS
[click logo to get started](#)


Those miniaturized components are designed in such a way that their internal reactance is very small. When correctly mounted and utilized, they function as almost pure resistors on a very large range of frequency, up to 50 GHz.

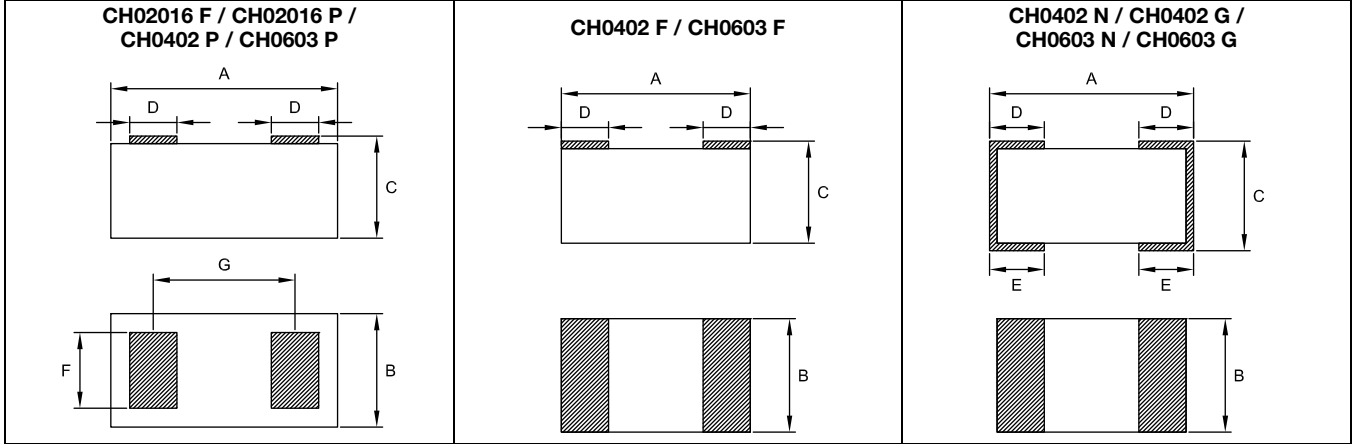
FEATURES

- Operating frequency 50 GHz
- Thin film microwave resistors
- Flip chip, wraparound or one face termination
- Small size, down to 20 mils by 16 mils
- Edged trimmed block resistors
- Pure alumina substrate (99.5 %)
- Ohmic range: 10R to 500R
- Design kits available
- Small internal reactance (LC down to 1×10^{-24})
- Tolerance 1 %, 2 %, 5 %, 10 %
- TCR: 100 ppm/°C in (-55 °C, +155 °C) temperature range
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
 COMPLIANT
 HALOGEN
FREE
GREEN
 (5-2008)

STANDARD ELECTRICAL SPECIFICATIONS

MODEL	SIZE	RESISTANCE RANGE Ω	RATED POWER P_n W	LIMITING ELEMENT VOLTAGE V	TOLERANCE \pm %	TEMPERATURE COEFFICIENT \pm ppm/°C
CH02016	02016	10 to 500	0.030	30	2, 5, 10	100
CH0402	0402	10 to 500	0.050	37	1, 2, 5, 10	100
CH0603	0603	10 to 500	0.125	50	1, 2, 5, 10	100

DIMENSIONS in millimeters (inches)


CASE SIZE MODEL / TERMINATION	DIMENSIONS						
	± 0.10 (± 0.004)	± 0.10 (± 0.004)	± 0.127 (± 0.005)	D E when applicable		± 0.050 (± 0.002)	± 0.050 (± 0.002)
				MIN.	MAX.		
CH02016 F CH02016 P	0.480 (0.020)	0.390 (0.016)	0.420 (0.016) ⁽¹⁾	0.110 (0.004)	0.150 (0.006)	0.260 (0.010)	0.300 (0.012)
CH0402 F CH0402 N CH0402 G	1.000 (0.040)	0.600 (0.023)	0.500 (0.020)	0.150 (0.006)	0.350 (0.014)	n/a	n/a
CH0402 P	1.200 (0.047)	0.600 (0.023)	0.500 (0.020)	0.110 (0.004)	0.150 (0.006)	0.320 (0.013)	0.880 (0.035)
CH0603 F CH0603 N CH0603 G	1.520 (0.060)	0.750 (0.030)	0.500 (0.020)	0.250 (0.010)	0.510 (0.020)	n/a	n/a
CH0603 P	1.720 (0.068)	0.750 (0.030)	0.500 (0.020)	0.235 (0.009)	0.275 (0.011)	0.660 (0.026)	1.355 (0.053)

Note
⁽¹⁾ ± 0.070 (± 0.003)

TOLERANCE VS. OHMIC VALUES

Ohmic range	$10 \Omega \leq R < 50 \Omega$	$50 \Omega \leq R < 100 \Omega$	$100 \Omega \leq R \leq 500 \Omega$
Tolerance	5 %, 10 %	2 %, 5 %, 10 %	1 %, 2 %, 5 %, 10 % ⁽¹⁾

Note

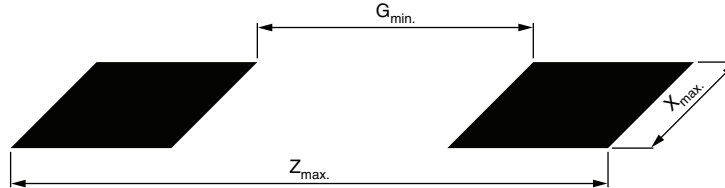
⁽¹⁾ 1 % tolerance not applicable for case 02016

LAND PATTERN FOR F 'FLIP CHIP' TERMINATIONS in millimeters (inches)


CHIP SIZE	Z _{max.}	X _{max.}	G _{min.}
02016	0.53 (0.021)	0.44 (0.017)	0.15 (0.006)
0402	1.40 (0.055)	0.65 (0.026)	0.40 (0.016)
0603	1.71 (0.067)	0.90 (0.035)	0.76 (0.030)

Note

- Suggested land pattern: According to IPC-7351

LAND PATTERN FOR N AND G WRAPAROUND TERMINATIONS in millimeters (inches)


CHIP SIZE	Z _{max.}	G _{min.}	X _{max.}
0402	1.55 (0.061)	0.15 (0.006)	0.73 (0.029)
0603	2.37 (0.093)	0.35 (0.014)	0.98 (0.039)

Dimension and tolerance of land pattern shall be defined by PCB designer; PCB can be designed according to IPC-7351A "Generic Requirements for Surface Mount Design and Land Pattern Standard"



PREFERRED MODELS AND VALUES

Vishay Sfernice highly recommend to use the smallest sizes and flip chip version to get the best performances.

Recommended Values:

10R/18R/25R/50R/75R/100R/150R/180R/200R/250R/330R/500R

Those values are available with a **MOQ of 100 pieces.**

Other values can be ordered upon request, but higher MOQ will apply: 1000 pieces for CH02016, 500 pieces for CH0402, 50 pieces for CH0603.

Recommended termination:

F

Recommended tolerance:

2 %

DESIGN KITS

Design kits are available Ex Stock in CH02016 and CH0402 sizes. There are 20 pieces per recommended value. F termination. 5 % tolerance.

Those kits are packaged in pieces of tape and delivered in ESD bags.

PACKAGING

Standard packaging is waffle pack for sizes 0402 and 0603 and plastic tape and reel (low conductivity) for size 02016.

Paper tape and reel is available for size 0402 and either paper tape and reel or plastic tape and reel (low conductivity) for size 0603.

Depending on the type of terminations, parts will be packed differently:

One face:

- Gold terminations: Active face up
- Tin/silver termination: Active face down

Note

- Please refer to Vishay Sfernice Application Note "Guidelines for Vishay Sfernice Resistive and Inductive Products" for soldering recommendation (document number 52029, 3. Guidelines for Surface Mounting Components (SMD), profile number 3 applies

SIZE	MOQ	NUMBER OF PIECES PER PACKAGE			TAPE WIDTH
		WAFFLE PACK 2" X 2"	TAPE AND REEL		
			Min.	Max.	
02016	See MOQ mentioned on preferred models and values	484	100	5000	8 mm
0402		100			
0603		100			

PACKAGING RULES

Waffle Pack

Can be filled up to maximum quantity indicated in the table here above, taking into account the minimum order quantity. When quantity ordered exceeds maximum quantity of a single waffle pack, the waffle packs are stacked up on the top of each other and closed by one single cover. To get "not stacked up" waffle pack in case of ordered quantity > maximum number of pieces per package: Please consult Vishay Sfernice for specific ordering code.

Tape and Reel

See Part Numbering information to get the quantity desired by tape.

In regard to the CH02016 size only, up to 5 empty cavities can be found every 1000 parts in the reel. Nevertheless, the number of requested parts will be respected.

The complex impedance of the chip resistor is given by the following equations:

$$Z = \frac{R + j\omega(L - R^2C - L^2C\omega^2)}{1 + C[(R^2C - 2L)\omega^2 + L^2C\omega^4]}$$

$$\frac{[Z]}{R} = \frac{1}{1 + C[(R^2C - 2L)\omega^2 + L^2C\omega^4]} \times \sqrt{1 + \left[\frac{\omega(L - R^2C - L^2C\omega^2)}{R}\right]^2}$$

$$\theta = \tan^{-1} \frac{\omega(L - R^2C - L^2C\omega^2)}{R}$$

Notes

- $\omega = 2 \times \pi \times f$
- f : Frequency

The chip resistor itself is purely resistive when $R = \sqrt{\frac{L}{C}}$. The smaller the L x C product the greater the frequency range over which the resistor looks approximately resistive.

This can be seen on the graphs showing the ratio $\frac{[Z]}{R}$ versus frequency.

R, L and C are relevant to the chip resistor itself.

L_c and C_g also depends on the way the chip resistor is mounted.

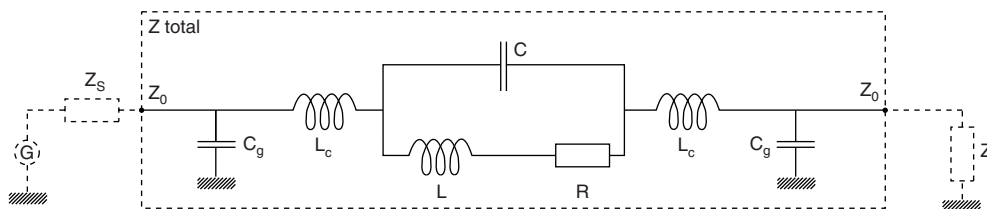
It is important to notice that after assembly the external reactance of L_c and C_g will be combined to internal reactance of L and C. This combination can upgrade or downgrade the HF behavior of the component.

This is why we are displaying two sets of data:

- $\frac{[Z]}{R}$ versus frequency curves which aims to show at a glance the intrinsic HF performance of a given chip resistor
- S-parameters versus frequency curves relevant to chip resistor when assembled on ideal Z_0 impedance transmission line

These lines are terminated with adapted source and load impedance respectively Z_s and Z_l with $Z_0 = Z_L = Z_s$ (for others configurations please consult us).

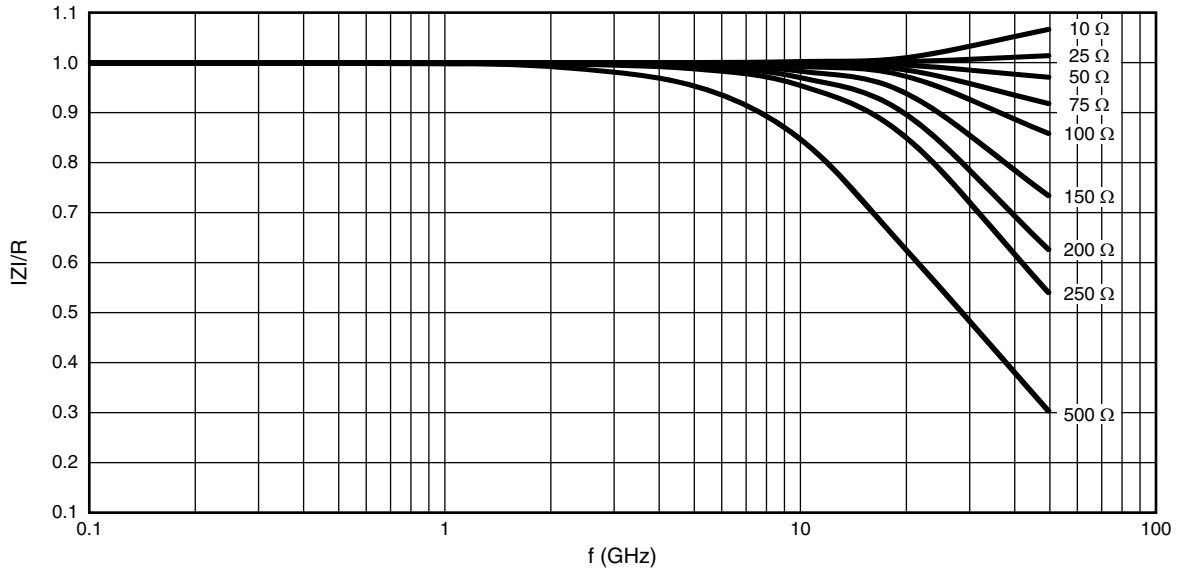
Equivalent circuit for S-parameters:



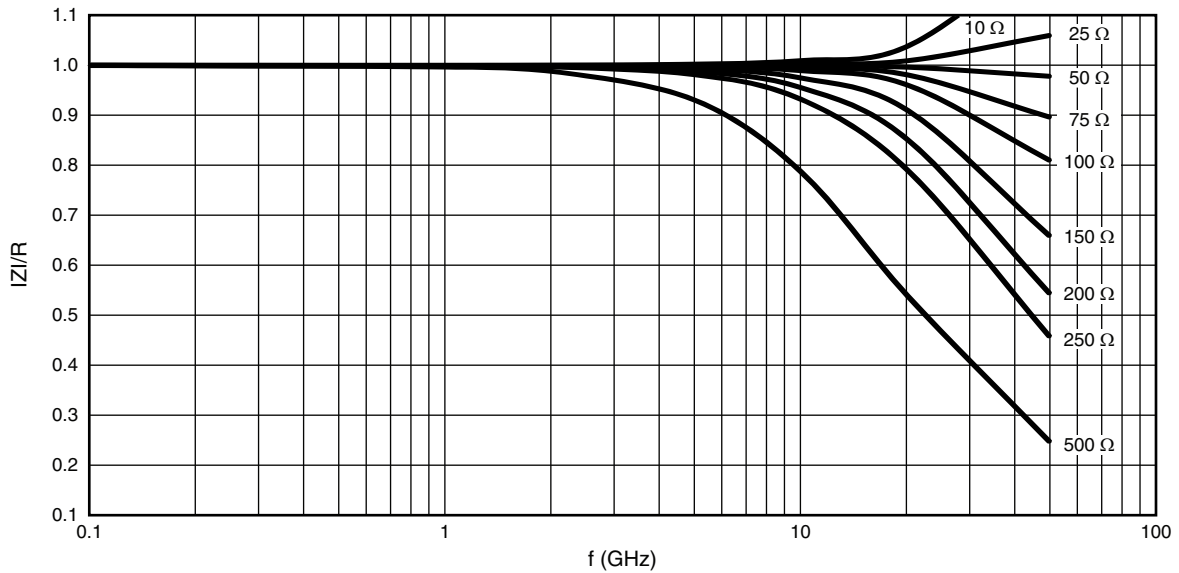
S-parameters are computed taking into account all the resistive, inductive and capacitive elements (Z_{total}) and $Z_0 = Z_L = Z_s = R$.



INTERNAL IMPEDANCE CURVES



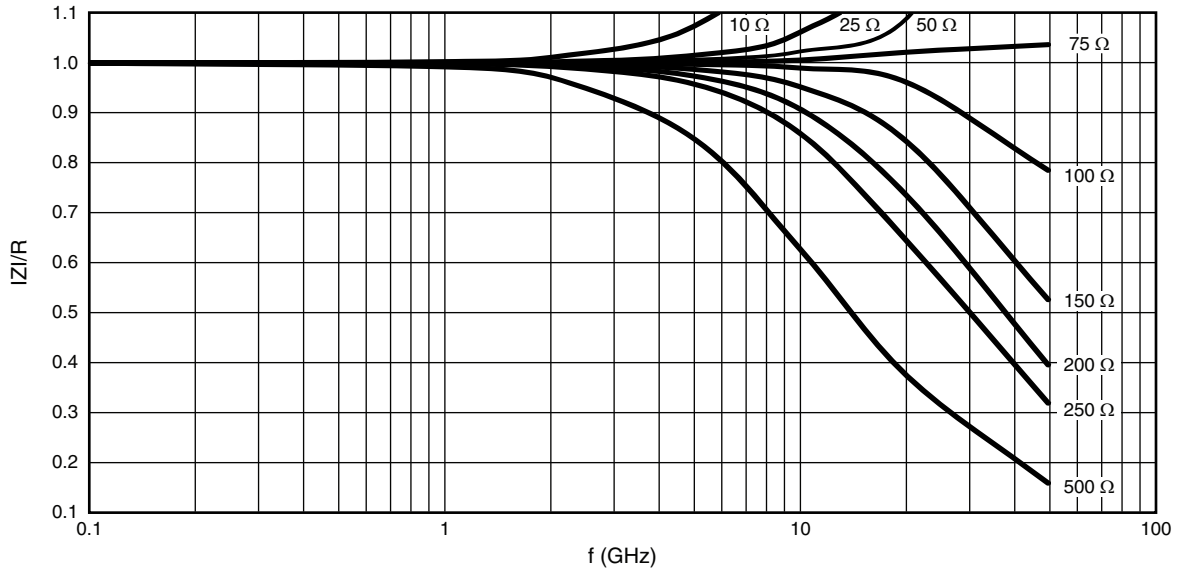
Internal impedance curve for 02016 size (F and P terminations)



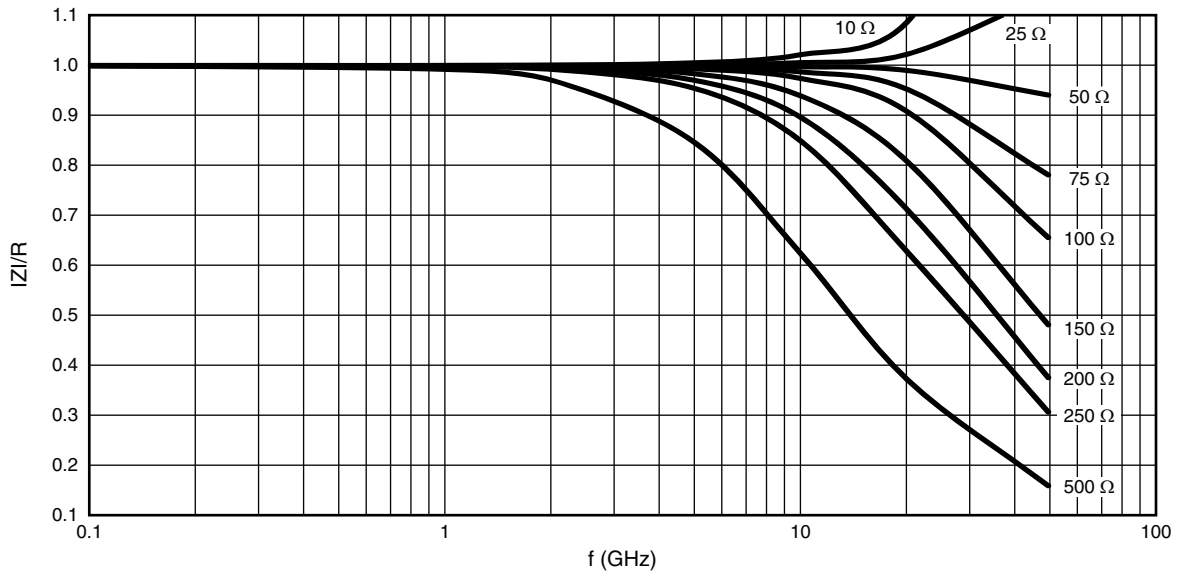
Internal impedance curve for 0402 size (F and P terminations)



INTERNAL IMPEDANCE CURVES



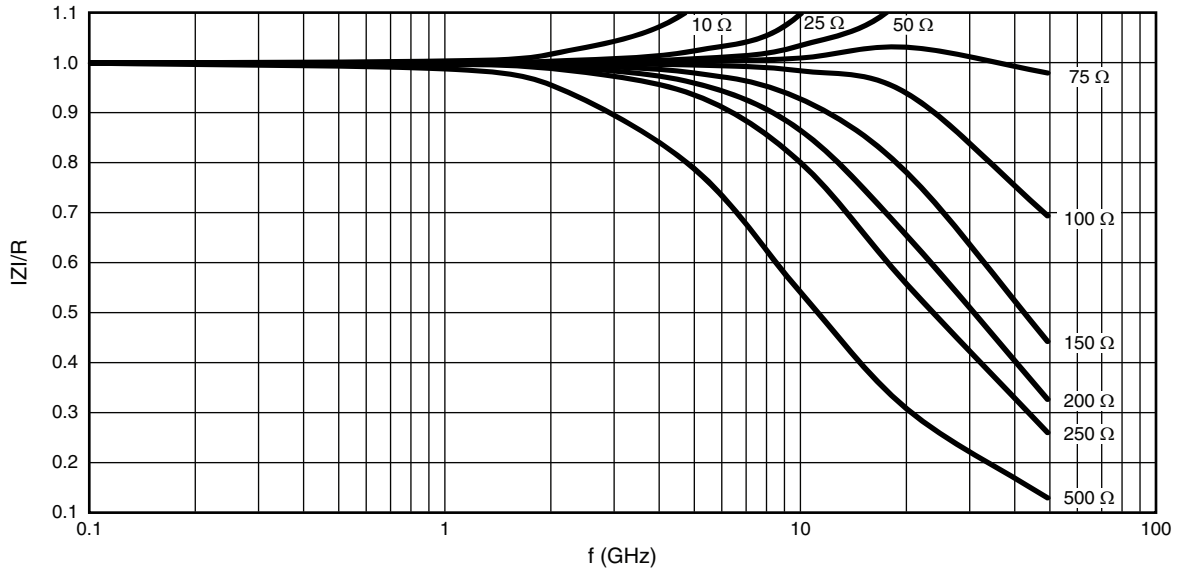
Internal impedance curve for 0402 size (N and G terminations)



Internal impedance curve for 0603 size (F and P terminations)



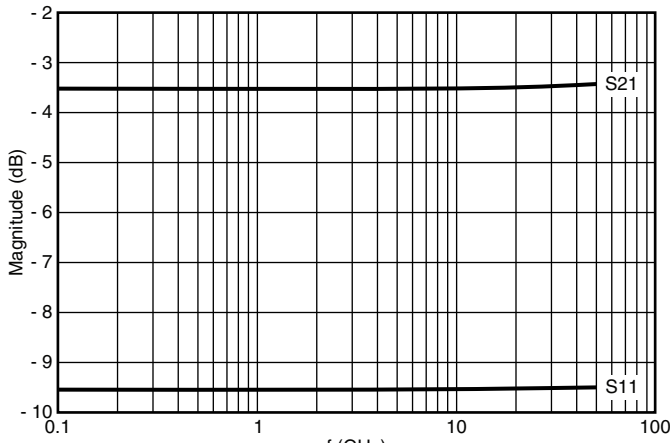
INTERNAL IMPEDANCE CURVES



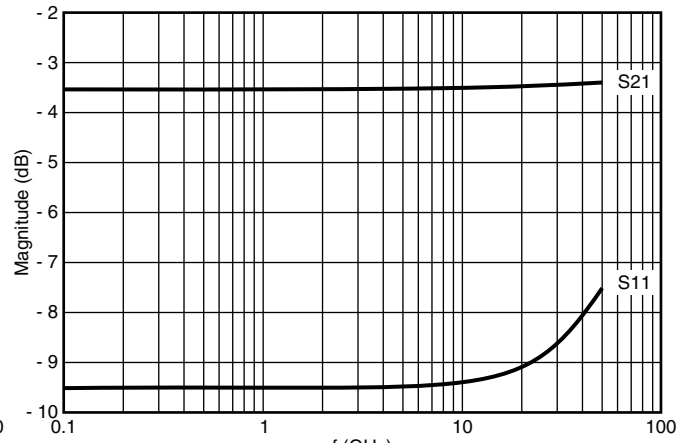
Internal impedance curve for 0603 size (N and G terminations)

S-PARAMETER

CH02016 (F and P Terminations)



CH02016 flip chip ($Z_0 = Z_1 = Z_s = R = 50 \Omega$)

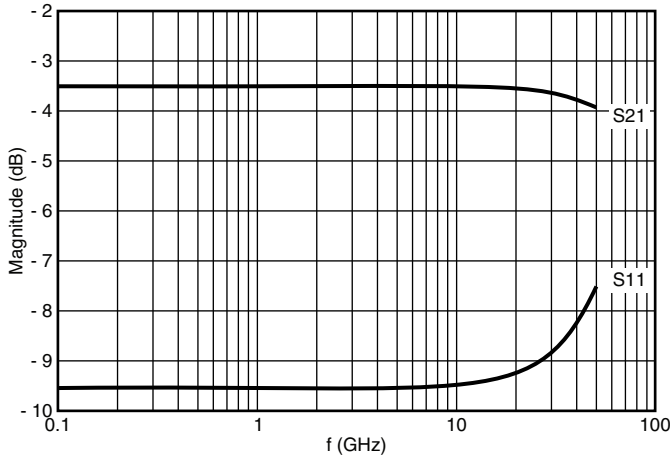


CH02016 flip chip ($Z_0 = Z_1 = Z_s = R = 100 \Omega$)

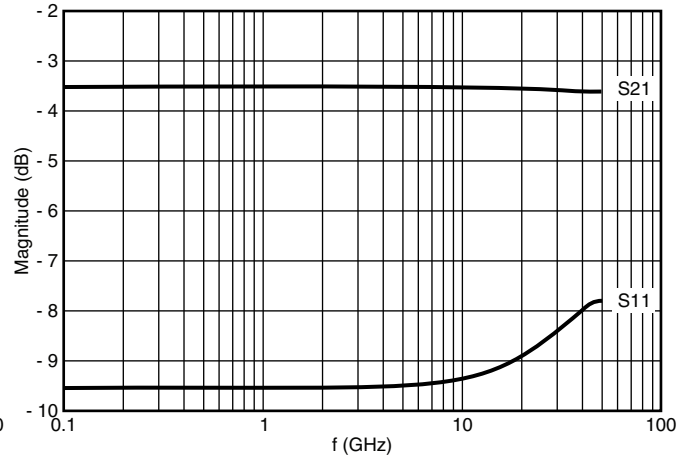


S-PARAMETER

CH0402 (F and P Terminations)

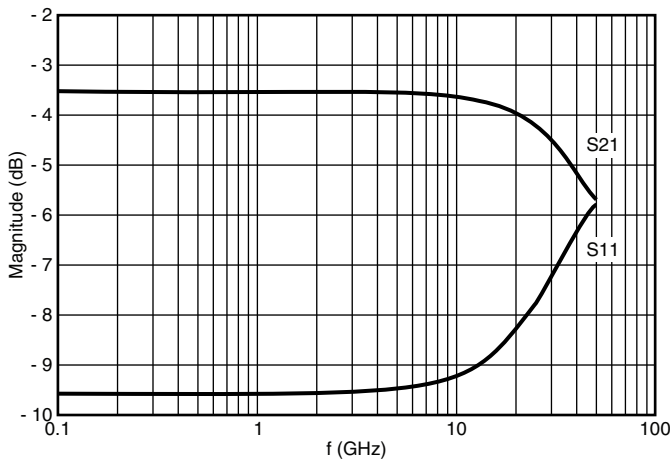


CH0402 flip chip ($Z_0 = Z_1 = Z_s = R = 50 \Omega$)

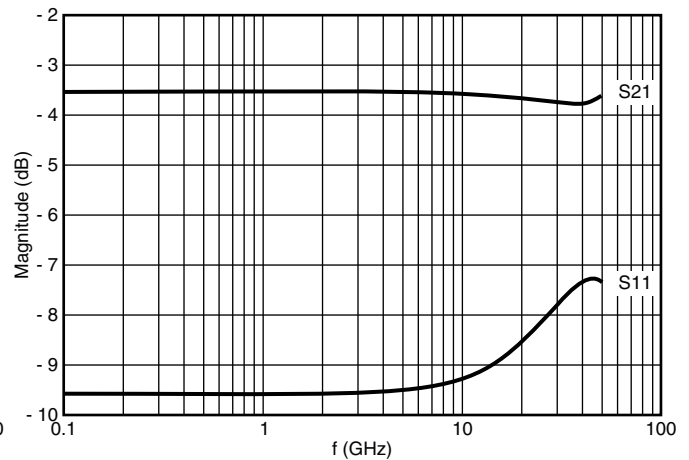


CH0402 flip chip ($Z_0 = Z_1 = Z_s = R = 100 \Omega$)

CH0402 (N and G Terminations)

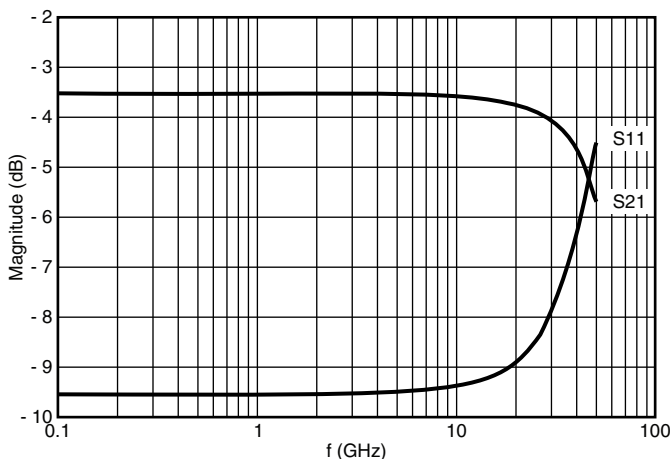


CH0402 wraparound ($Z_0 = Z_1 = Z_s = R = 50 \Omega$)

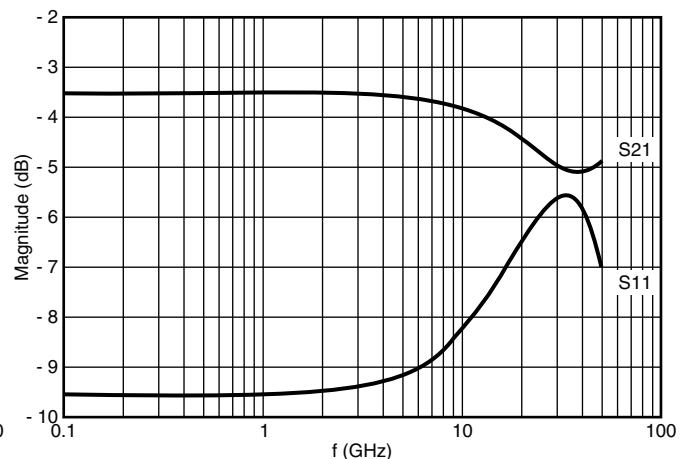


CH0402 wraparound ($Z_0 = Z_1 = Z_s = R = 100 \Omega$)

CH0603 (F and P Terminations)



CH0603 flip chip ($Z_0 = Z_1 = Z_s = R = 50 \Omega$)

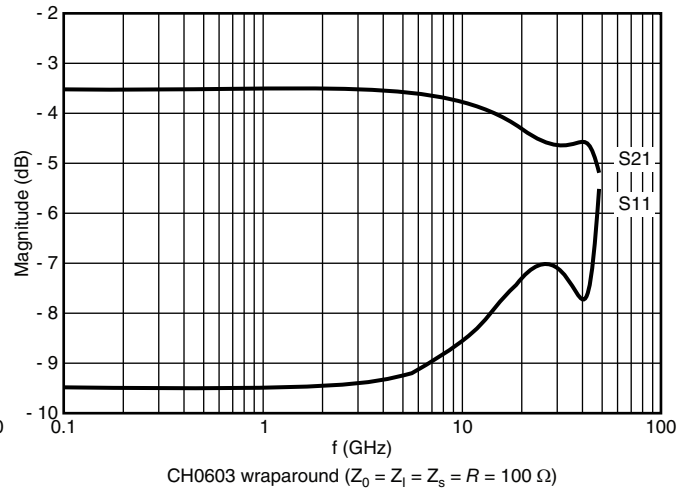
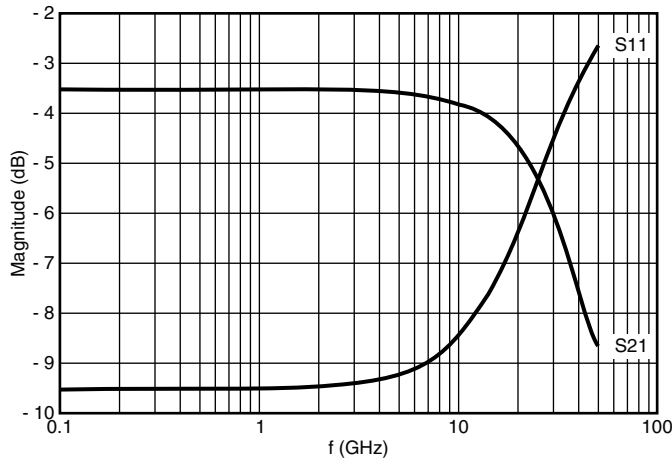


CH0603 flip chip ($Z_0 = Z_1 = Z_s = R = 100 \Omega$)



S-PARAMETER

CH0603 (N and G Terminations)





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